

Technical data sheet

**PROPERTIES
THERMAL E**

The values are measured on standard Thermal E, with copper surface of 35μ, dielectric of 0.10mm, aluminium of 1.50 mm.

Produced with epoxy multifunctional and dysfunctional epoxy resin

	TEST METHOD	TEST CONDITIONS	UNITS	TYPICAL VALUE
THERMAL STRESS	IPC 2.4.1.3.1.	288°C (550,4°F)	min.	3
COPPER PEEL	IPC 2.4.8.2.	20s/288°C	N/cm ²	16
DIEL BREAKDOWN	IPC 650	A		6
DIEL BREAKDOWN AFTER 500h at 500°C	IPC 2.5.6.650	E 500/150	KW	4
DIEL BREAKDOWN AFTER WATER IMMERSION	IPC 2.5.6.650	D 48/50	KW	3
THERMAL CONDUCTIVITY	ASTM-D5470	60°C	W/m/k	4/6
SURFACE RESISTANCE	IPC 2.5.1.7.1	C 96/35/90	MΩ	1.10X10*6
RELATIVE PERMITTIVITY AU MHZ	IPC 2.5.5.3		1 MHz	0.018
DISSIPATION FACTOR	IPC 2.5.5.3		1 MHz	4.7CM °K
COMPARATIVE TRACKING INDEX CTI			200	
GLASS TRANSITION . TEMPERATURE OF DIELECTRIC LAYER	IPC-TM150	A	°C	130
FLAMMABILITY UL 94			V0	
MOISTURE ABSORBTION	IPC 2.6.2.1	D 24/23	%	Max 0.15
THERMAL TEST CONDUCTIVITY	EVALUATED ON INSULATING THICKNESS OF 0.1mm			